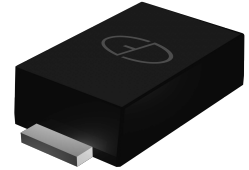


Features

- Low leakage current
- Low forward voltage drop
- Glass passivated chip junction
- Moisture sensitivity: level 1, per J-STD-020
- High temperature soldering guaranteed: 260°C /10 seconds
- Halogen-free according to IEC 61249-2-21 definition



RoHS
COMPLIANT



Package: eSGA
(SOD-123FL)

Applications

For use of fast switching rectification in lighting, cellular phone, portable device, power supplies and other consumer applications.

Maximum Ratings (T_A=25°C unless otherwise noted)

Parameter	Symbol	FH1	FH2	FH3	FH4	FH5	FH6	FH7	Unit
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	I _{F(AV)}	1							A
Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load Per Diode	I _{FSM}	30							A
Typical Thermal Resistance, Junction to Ambient ¹	R _{θJA}	100							°C/W
Typical Thermal Resistance, Junction to Case ¹	R _{θJC}	20							°C/W
Typical Thermal Resistance, Junction to Lead ¹	R _{θJL}	20							°C/W
Operating Junction Temperature Range	T _J	-55 to +150							°C
Storage Temperature Range	T _{STG}	-55 to +150							°C

Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	FH1	FH2	FH3	FH4	FH5	FH6	FH7	Unit
Forward Drop Voltage	V _F	I _F =1A	1.3			1.7			V	
Reverse Leakage Current @ V _R	I _R	T _J =25°C	5							uA
		T _J =125°C	100							
Maximum Reverse Recovery Time	t _{rr}	I _F =0.5A, I _R =1.0A, I _{RR} =0.25A	50			75			nS	

Note:

1. Mounted on copper pad area of 0.2x0.2" (5.0 x 5.0mm) to each terminal.

Ratings and Characteristics Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

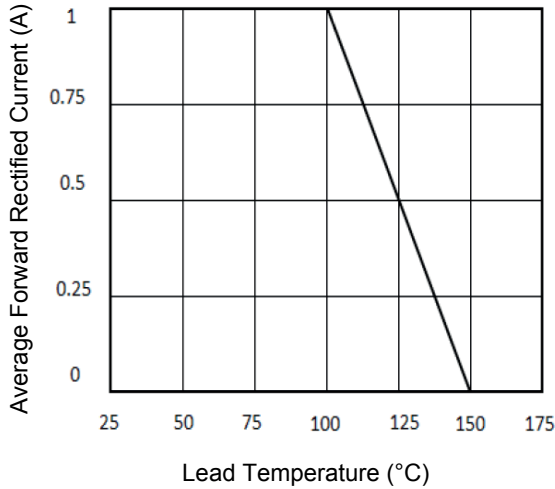


Figure 1. Forward Current Derating Curve

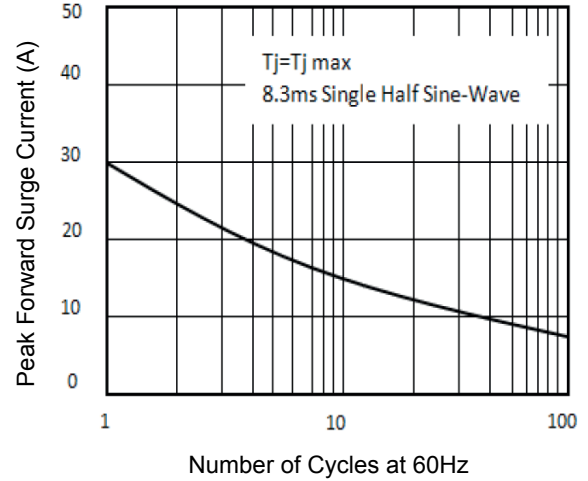


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

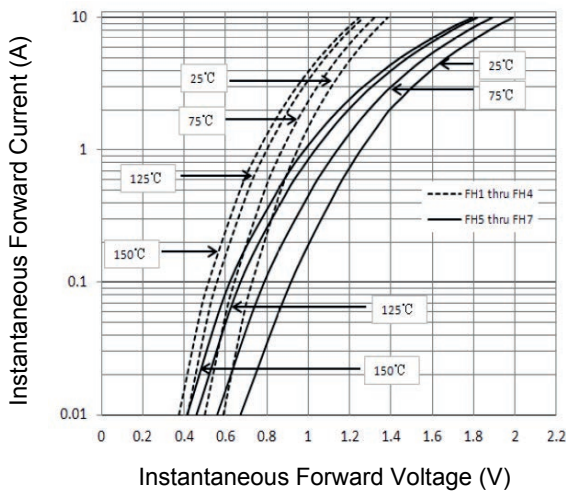


Figure 3. Typical Instantaneous Forward Characteristics

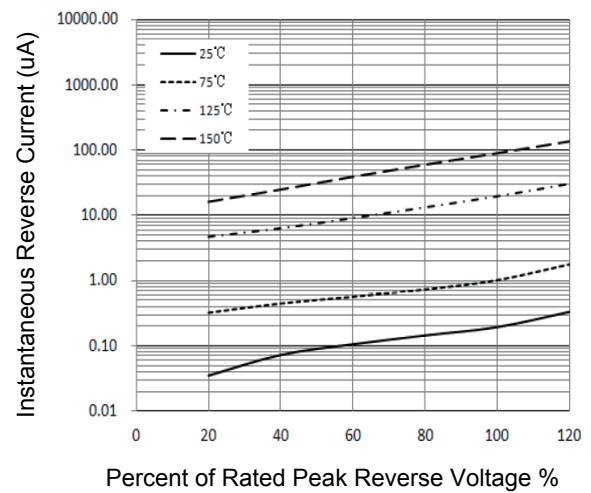
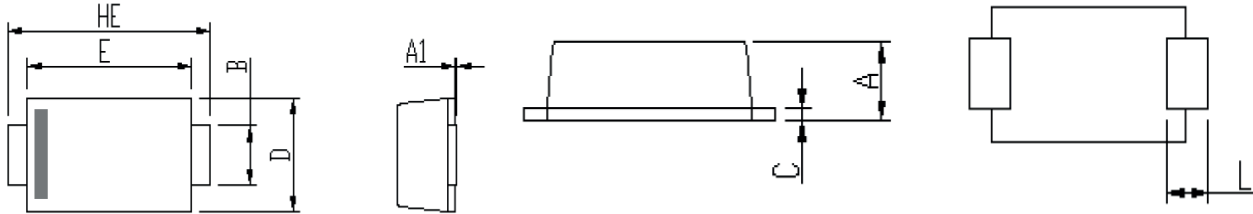


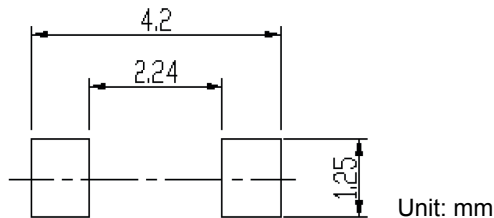
Figure 4. Typical Reverse Characteristics

Package Outline Dimensions eSGA (SOD-123FL)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.90	1.08	0.035	0.043
A1	0.00	0.10	0.000	0.004
B	0.85	1.05	0.033	0.041
C	0.10	0.25	0.004	0.010
D	1.70	2.00	0.067	0.079
E	2.90	3.10	0.114	0.122
L	0.43	0.83	0.017	0.033
HE	3.50	3.90	0.138	0.154

Recommended Pad Layout



Order Information

Device	Package	Marking	Quantity
FH1	eSGA (SOD-123FL)	H1	3,000pcs / Reel
FH2	eSGA (SOD-123FL)	H2	3,000pcs / Reel
FH3	eSGA (SOD-123FL)	H3	3,000pcs / Reel
FH4	eSGA (SOD-123FL)	H4	3,000pcs / Reel
FH5	eSGA (SOD-123FL)	H5	3,000pcs / Reel
FH6	eSGA (SOD-123FL)	H6	3,000pcs / Reel
FH7	eSGA (SOD-123FL)	H7	3,000pcs / Reel

For more information, please contact us at: inquiry@goodarksemi.com